

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired. NOTES:

1) These ratings are based on a maximum junction temperature of 200 degrees C.
2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics

Symbol	Parameter	Value	Units
P _D	Power Dissipation	500	mW
$R_{ ext{ hetaJA}}$	Thermal Resistance, Junction to Ambient	300	°C/W

Electrical Characteristics T₄ = 25°C unless otherwise noted

Symbol	Parameter		Test Conditions	Min	Max	Units
V _R	Breakdown Voltage	BAV19	I _R = 100 μA	120		V
		BAV20	I _R = 100 μA	200		V
		BAV21	I _R = 100 μA	250		V
V _F	Forward Voltage		I _F = 100 mA		1.0	V
	_		I _F = 200 mA		1.25	V
I _R	Reverse Current		V _R = 100 V		100	nA
		BAV19	V _R = 100 V, T _A = 150°C		100	μΑ
			V _R = 150 V		100	nA
		BAV20	V _R = 150 V, T _A = 150°C		100	μΑ
			V _R = 200 V		100	nA
		BAV21	V _R = 200 V, T _A = 150°C		100	μΑ
CT	Total Capacitance		$V_{R} = 0, f = 1.0 \text{ MHz}$		5.0	pF
t _{rr}	Reverse Recovery Time		$I_F = I_R = 30 \text{ mA}, I_{RR} = -3.0 \text{ mA}, R_1 = 100\Omega$		50	ns

Units

V

V

V

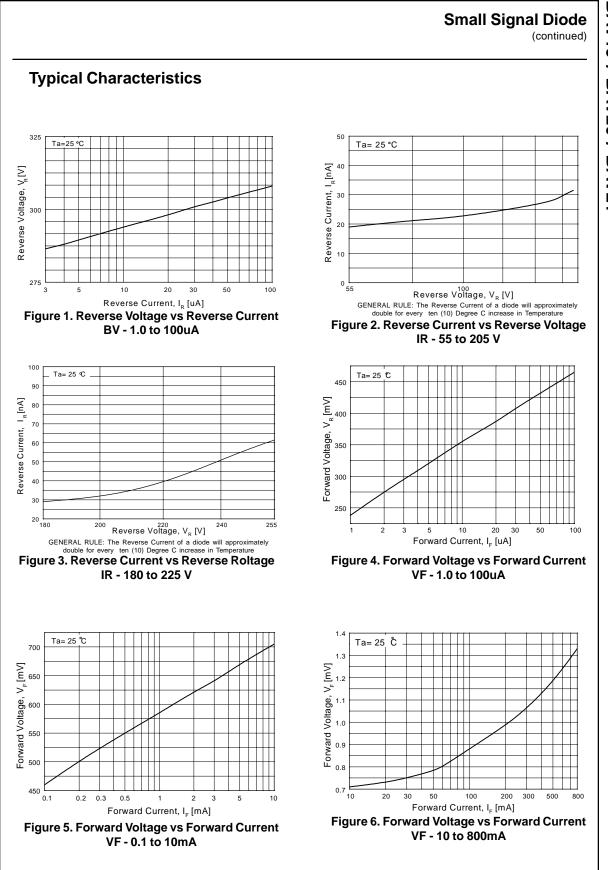
mΑ

А

А

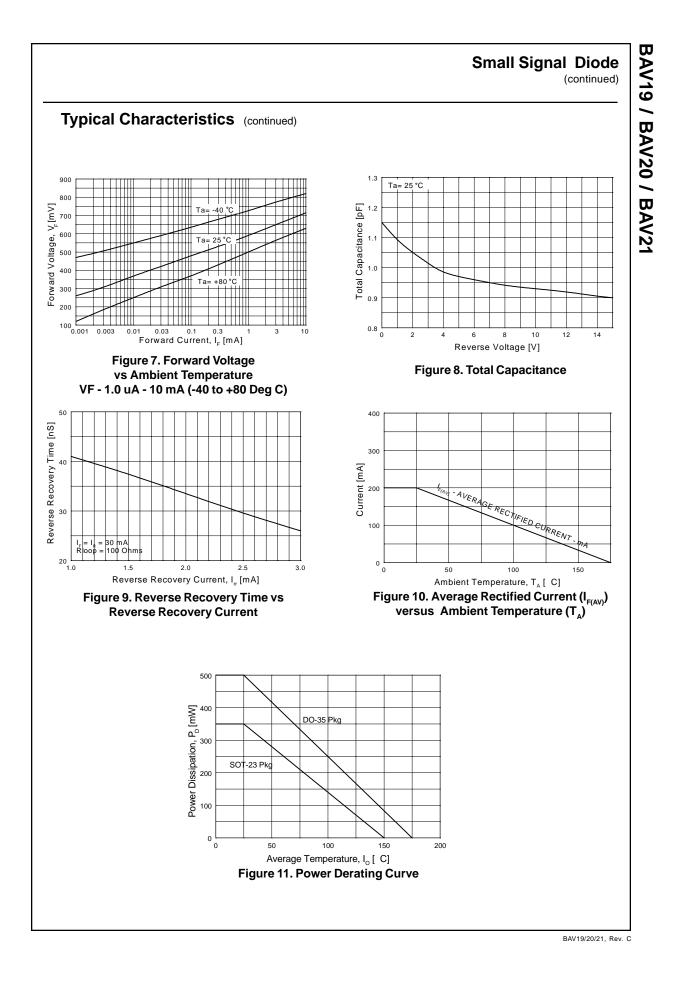
°C

°C



BAV19/20/21, Rev. C

BAV19 / BAV20 / BAV21



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